August 2001

IGBT

SGR20N40L / SGU20N40L

General Description

Insulated Gate Bipolar Transistors (IGBTs) with a trench gate structure provide superior conduction and switching performance in comparison with transistors having a planar gate structure. They also have wide noise immunity. These devices are very suitable for strobe applications

Features

- · High input impedance
- High peak current capability (150A)
- · Easy gate drive
- Surface Mount : SGR20N40LStraight Lead : SGU20N40L

Application

Strobe flash.







Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description	SGR / SGU20N40L	Units
V _{CES}	Collector - Emitter Voltage	400	V
V _{GES}	Gate - Emitter Voltage	± 6	V
I _{CM (1)}	Pulsed Collector Current	150	Α
P _C	Maximum Power Dissipation @ T _C = 25	5°C 45	W
TJ	Operating Junction Temperature	-40 to +150	°C
T _{stg}	Storage Temperature Range	-40 to +150	°C
T _L	Maximum Lead Temp. for soldering purposes, 1/8" from case for 5 seconds	300	°C

Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		3.0	°C/W
R _{θJA} (D-PAK)	Thermal Resistance, Junction-to-Ambient (PCB Mount) (2)		50	°C/W
R _{θJA} (I-PAK)	Thermal Resistance, Junction-to-Ambient		110	°C/W

Notes :

(2) Mounted on 1" square PCB (FR4 or G-10 Material)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Cha	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V$, $I_C = 1mA$	450			V
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			10	μΑ
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 0.1	μΑ
	racteristics	1			1	1
$V_{GE(th)}$	G-E Threshold Voltage	$I_C = 1 \text{ mA}, V_{CE} = V_{GE}$	0.5	1.0	1.4	V
V _{CE(sat)}	C-E Saturation Current	$I_C = 150A, V_{GE} = 4.5V$	2.0	4.5	8.0	V
Dynami C _{ies}	c Characteristics	I		3800		рF
C _{oes}	Output Capacitance	$V_{GE} = 0V, V_{CE} = 30V,$		50		рF
	Output Oapacitarioc	f = 1MHz		35		ρF
Cros	Reverse Transfer Capacitance					
C _{res}	Reverse Transfer Capacitance ng Characteristics					
_{Cres} Switchii		V 200V L 150A		0.2		μs
C _{res} Switchii t _{d(on)}	ng Characteristics	V _{CC} = 300V, I _C = 150A,				μs μs
C _{res}	ng Characteristics Turn-On Delay Time	$V_{CC} = 300V, I_{C} = 150A,$ $V_{GE} = 4.5V, R_{G} = 15\Omega^{*}$ Resistive Load		0.2	 0.5	•

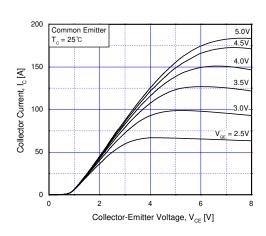


Fig 1. Typical Output Characteristics

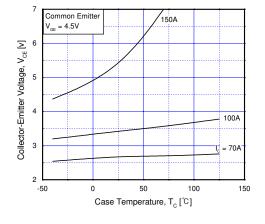


Fig 2. Saturation Voltage vs. Case
Temperature at Variant Current Level

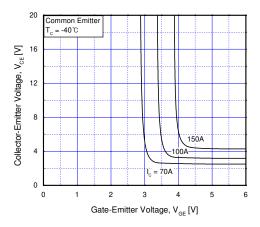


Fig 3. Saturation Voltage vs. V_{GE}

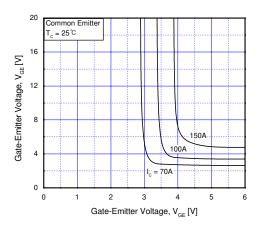


Fig 4. Saturation Voltage vs. V_{GE}

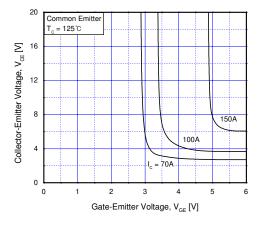


Fig 5. Saturation Voltage vs. V_{GE}

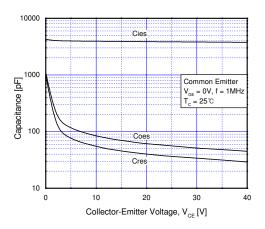
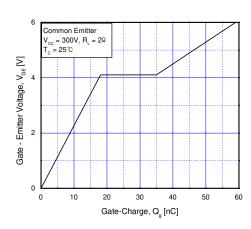


Fig 6. Capacitance Characteristics

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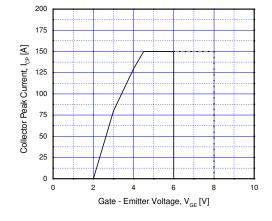


Fig 7. Turn-On Characteristics vs.
Gate Resistance

Fig 8. Collector Current Limit vs.
Gate - Emitter Voltage Limit

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